

June 2014

# 74LVX3245 8-Bit, Dual-Supply Translating Transceiver with 3-State Outputs

#### **Features**

- Bidirectional Interface Between 3 V and 5 V Buses
- Inputs Compatible with TTL Level
- 3 V Data Flow at A-Port and 5 V Data Flow at B-Port
- Outputs Source / Sink: 24 mA
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance
- Implements Proprietary EMI Reduction Circuitry
- Functionally Compatible with the 74 Series 245

## **Description**

The 74LVX3245 is a dual-supply, 8-bit translating transceiver designed to interface between a 3 V bus and a 5 V bus in a mixed 5 V supply environment. The Transmit/ Receive (T/R) input determines the direction of data flow. Transmit (active-HIGH) enables data from A-ports to B-ports; receive (active-LOW) enables data from B-ports to A-ports. The output enable input, when HIGH, disables both A- and B-ports by placing them in a high-impedance condition. The A-port interfaces with the 3 V bus; the B-port interfaces with the 5 V bus.

The 74LVX3245 is suitable for mixed-voltage applications, such as notebook computers using 3.3 V CPU and 5V peripheral components.

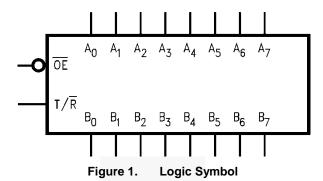
#### **Related Resources**

 AN-5001 — Using Fairchild's LVX Low-Voltage Dual-Supply CMOS Translating Transceivers

# **Ordering Information**

Part Number	Operating Temperature Range	Package	Packing Method
74LVX3245WM		24-Lead Small-Outline Integrated Circuit	Tubes
74LVX3245WMX		(SOIC), JEDEC MS-013, 0.300" Wide	Tape and Reel
74LVX3245QSC		24-Lead Quarter-Size Outline Package	Tubes
74LVX3245QSCX	-40 to +85°C	(QSOP), JEDEC MO-137, 0.150" Wide	Tape and Reel
74LVX3245MTC		24-Lead Thin-Shrink Small-Outline	Tubes
74LVX3245MTCX		Package (TSSOP), JEDEC MO-153, 4.4 mm Wide	Tape and Reel

# **Logic Symbol**



# **Pin Configuration**

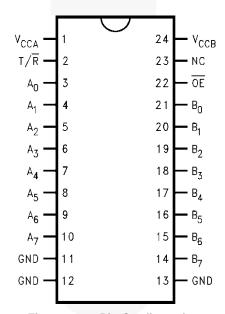


Figure 2. Pin Configuration

# **Pin Definitions**

Pin #	Name	Description
1	V <sub>CCA</sub>	Supply Voltage
2	T/R	Transmit/Receive Input
3, 4, 5, 6, 7, 8, 9, 10 A <sub>0</sub> , A <sub>1</sub> , A <sub>2</sub> , A <sub>3</sub> , A <sub>4</sub> , A <sub>5</sub> , A <sub>6</sub> , A <sub>7</sub>		Port-A Inputs or 3-State Outputs
11, 12, 13	GND	Ground
14, 15, 16, 17, 18, 19, 20, 21	B <sub>7</sub> , B <sub>6</sub> , B <sub>5</sub> , B <sub>4</sub> , B <sub>3</sub> , B <sub>2</sub> , B <sub>1</sub> , B <sub>0</sub>	Port-B Inputs or 3-State Outputs
22	/OE	Output Enable Input
23	NC	No Connect
24	V <sub>CCB</sub>	Supply Voltage

# **Logic Diagram**

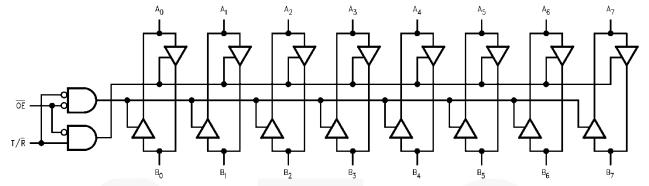


Figure 3. Logic Diagram

Table 1. Truth Table

Inp	outs	Outputs
/OE	T/R	
L	L	Bus B Data to Bus A
L	Н	Bus A Data to Bus B
Н	X	HIGH-Z State

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	P	arameter		Min.	Max.	Unit	
V <sub>CCA</sub> , V <sub>CCB</sub>	Supply Voltage			-0.5	7.0	V	
V <sub>IN</sub>	DC Input Voltage; (/OE, T/R)					V	
V	DC Input / Output Voltage		An	-0.5	V <sub>CCA</sub> to +0.5	V	
V <sub>I/O</sub>	DC Input / Output Voltage		Bn	-0.5	V <sub>CCB</sub> to +0.5	V	
I <sub>IN</sub>	DC Input Diode Current (/OE and T/R)				±20	mA	
I <sub>OK</sub>	DC Output Diode Current				±50	mA	
Io	DC Output Source or Sink Current				±50	mA	
	Output Pin				±50		
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	Maximum Cumant at	I <sub>CCA</sub>		±100	mA	
		Maximum Current at	I <sub>CCB</sub>		±200		
T <sub>STG</sub>	Storage Temperature Range			-65	+150	°C	
I <sub>SINK</sub>	DC Latch-Up Source or Sink Current				±300	mA	
TJ	Maximum Junction Temperature Under Bias				+150	°C	
ESD	Electrostatic Discharge Capability	Human Body Model, JE	SD22-A114		2500	V	

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter		Min.	Max.	Unit
$V_{CCA}$	Cumply Voltage	2.7	3.6	W	
V <sub>CCB</sub>	Supply Voltage	4.5	5.5	V	
Vı	Input Voltage (/OE and T/R)	0	V <sub>CCA</sub>	V	
\/	DC Input / Output Voltage	A <sub>n</sub>	0	V <sub>CCA</sub>	V
$V_{I/O}$	DC Input / Output Voltage	B <sub>n</sub>	0	V <sub>CCB</sub>	V
T <sub>A</sub>	Operating Temperature, Free Air		-40	+85	°C
Δt / ΔV	Minimum Input Edge Rate (V <sub>IN</sub> from 30 to 70% of V <sub>CC</sub> , V <sub>CC</sub> a 4.5 V, and 5.5 V)	at 3.0 V,		8	ns/V

#### Note:

1. Unused pins (inputs and I/O's) must be held HIGH or LOW. They may not float.

# **DC Electrical Characteristics**

Comple ed	Davama	-1	Conditions	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = -	25°C	T <sub>A</sub> =-40 to+85°C	l lmita	
Symbol	Parame	eter	Conditions	(V)	(V)	Тур.	Gua	ranteed Limits	Units	
		A <sub>n</sub> , T/R ,		3.6	5.0		2.0	2.0		
$V_{IHA}$	Minimum	/OE	V <sub>OUT</sub> ≤ 0.1 V or	2.7	5.0		2.0	2.0		
	HIGH Level Input Voltage	_	≥ V <sub>CC</sub> - 0.1 V	3.3	4.5		2.0	2.0	V	
$V_{IHB}$	p a v aag a	B <sub>n</sub>		3.3	5.5		2.0	2.0		
		A <sub>n</sub> , T/R ,		3.6	5.0		0.8	0.8		
$V_{ILA}$	Minimum	/OE	V <sub>OUT</sub> ≤ 0.1 V or	2.7	5.0		0.8	0.8		
	LOW Level Input Voltage	_	≥ V <sub>CC</sub> - 0.1 V	3.3	4.5		0.8	0.8	V	
$V_{ILB}$	p a v aag a	B <sub>n</sub>		3.3	5.5		0.8	0.8		
			I <sub>OUT</sub> =-100 μA	3.0	4.5	2.99	2.90	2.90		
			I <sub>OH</sub> =-24 mA	3.0	4.5	2.65	2.35	2.25		
$V_{OHA}$	Minimum HIG	H Level	I <sub>OH</sub> =-12 mA	2.7	4.5	2.50	2.30	2.20		
	Output Voltag		I <sub>OH</sub> =-24 mA	2.7	4.5	2.30	2.10	2.00	V	
/			Ι <sub>Ουτ</sub> =-100 μΑ	3.0	4.5	4.50	4.40	4.40		
$V_{OHB}$			I <sub>OH</sub> =-24 mA	3.0	4.5	4.25	3.86	3.76		
	/ /		I <sub>OUT</sub> =100 μA	3.0	4.5	0.002	0.100	0.100		
.,			I <sub>OH</sub> =24 mA	3.0	4.5	0.210	0.360	0.440	N .	
$V_{OLA}$	Minimum LOW Level		I <sub>OH</sub> =12 mA	2.7	4.5	0.110	0.360	0.440		
	Output Voltage		I <sub>OH</sub> =24 mA	2.7	4.5	0.220	0.420	0.500	V	
.,			Ι <sub>Ουτ</sub> =100 μΑ	3.0	4.5	0.002	0.100	0.100		
$V_{OLB}$			I <sub>OH</sub> =24 mA	3.0	4.5	0.180	0.360	0.440		
I <sub>IN</sub>	Maximum Inpl Leakage Curr /OE, T/R		V <sub>IN</sub> =V <sub>CCB</sub> , GND	3.6	5.5		±0.1	±1.0	μΑ	
I <sub>OZA</sub>	Maximum 3-S Output Leaka		V <sub>IN</sub> =V <sub>IL</sub> , V <sub>IH</sub> ; /OE= V <sub>CCA</sub> ; V <sub>O</sub> =V <sub>CCA</sub> , GND	3.6	5.5		±0.5	±5.0	μΑ	
I <sub>OZB</sub>	Maximum 3-S Output Leaka		V <sub>IN</sub> =V <sub>IL</sub> , V <sub>IH</sub> ; /OE= V <sub>CCA</sub> ; V <sub>O</sub> =V <sub>CCB</sub> , GND	3.6	5.5		±0.5	±5.0	μΑ	
	Maximum	B <sub>n</sub>	V <sub>IN</sub> =V <sub>CCB</sub> -2.1 V	3.6	5.5	1.00	1.35	1.50		
Δlcc	Maximum I <sub>CCT</sub> /Input at A <sub>n</sub> , T/R , /OE		V <sub>IN</sub> =V <sub>CCA</sub> -0.6 V	3.6	5.5		0.35	0.50	mA	
I <sub>CCA</sub>	Quiescent V <sub>CCA</sub> Supply Current		$\begin{array}{l} A_n = V_{CCA} \text{ or GND,} \\ B_n = V_{CCB} \text{ or GND,} \\ /OE = GND, \\ T/R = GND \end{array}$	3.6	5.5		5	50		
I <sub>CCB</sub>	Quiescent V <sub>CCB</sub> Supply Current		A <sub>n</sub> =V <sub>CCA</sub> or GND, B <sub>n</sub> =V <sub>CCB</sub> or GND, /OE=GND, T/R =V <sub>CCA</sub>	3.6	5.5		8	80	μА	

Continued on the following page...

# **DC Electrical Characteristics** (Continued)

Symbol	Parameter	Conditions	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = -25°C	T <sub>A</sub> =-	40 to+85°C	Units
Syllibol	Farameter	Conditions	(V)	(V)	Тур.	Guara	<b>Guaranteed Limits</b>	
$V_{OLPA}$	Quiet Output Maximum Dynamic V <sub>OL</sub> <sup>(2, 3)</sup>		3.3	5.0		0.8		V
$V_{OLPB}$	Dynamic V <sub>OL</sub> <sup>(2, 3)</sup>		3.3	5.0		1.5		V
$V_{OLVA}$	Quiet Output Minimum Dynamic V <sub>OL</sub> <sup>(2, 3)</sup>		3.3	5.0		-0.8		V
$V_{OLVB}$			3.3	5.0		-1.2		V
$V_{IHDA}$	Minimum HIGH Level		3.3	5.0		2.0		
V <sub>IHDB</sub>	Dynamic Input Voltage <sup>(2, 4)</sup>		3.3	5.0		2.0		V
V <sub>ILDA</sub>	Maximum LOW Level		3.3	5.0		0.8		
V <sub>ILDB</sub>	Dynamic Input Voltage <sup>(2, 4)</sup>		3.3	5.0		0.8		V

#### Notes:

- Worst-case package.
- 3.
- Maximum number of outputs defined as (n). Data inputs are driven 0 V to  $V_{CC}$  level; one output at GND. Maximum number of data inputs (n) switching. (n-1) inputs switching 0 V to  $V_{CC}$  level. Input-under-test switching;  $V_{CC}$  level to threshold ( $V_{IHD}$ ), 0V to threshold ( $V_{ILD}$ ), f=1 MHz.

## **AC Electrical Characteristics**

Symbol	Parameter	$T_A=+25^{\circ}C$ , $C_L=50$ pF, $V_{CCA}=3.3~V^{(5)}$ , $V_{CCB}=5.0~V^{(6)}$		T <sub>A</sub> =-40 to C <sub>L</sub> =50 V <sub>CCA</sub> =3 V <sub>CCB</sub> =5	0 pF, .3 V <sup>(5)</sup> ,	$T_A$ =-40 to +85°C, $C_L$ =50 pF, $V_{CCA}$ =2.7 V, $V_{CCB}$ =5.0 V		Units	
		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
	Propagation	1.0	5.4	8.0	1.0	8.5	1.0	9.0	
	Delay A to B	1.0	5.6	7.5	1.0	8.0	1.0	8.5	no
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation	1.0	5.1	7.5	1.0	8.0	1.0	8.5	ns -
	Delay B to A	1.0	5.7	7.5	1.0	8.0	1.0	8.5	
	Output Enable Time /OE to B	1.0	4.8	8.0	1.0	8.5	1.0	9.0	- ns
		1.0	6.3	8.5	1.0	9.0	1.0	9.5	
$t_{PZL}, t_{PZH}$	Output Enable	1.0	6.3	8.5	1.0	9.0	1.0	9.5	
	Time /OE to A	1.0	6.8	9.0	1.0	9.5	1.0	10.0	
	Output Disable	1.0	5.3	7.5	1.0	8.0	1.0	8.5	
/	Time /OE to B	1.0	4.2	7.0	1.0	7.5	1.0	8.0	- ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Output Disable	1.0	5.3	8.0	1.0	8.5	1.0	9.0	
	Time /OE to A	1.0	3.7	6.5	1.0	7.0	1.0	7.5	
t <sub>OSHL</sub> , t <sub>OSLH</sub>	Output to Output Skew, Data to Output <sup>(7)</sup>		1.0	1.5		1.5		1.5	ns

#### Notes:

- 5. Voltage range 3.3 V is  $3.3 \text{ V} \pm 0.3 \text{ V}$ .
- 6. Voltage range 5.0 V is 5.0 V  $\pm$  0.5 V.
- 7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshl) or LOW-to-HIGH (toslh). Parameter guaranteed by design.

# Capacitance

Symbol	Parameter	Conditions	Тур.	Units	
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open	4.5	pF	
C <sub>I/O</sub>			V <sub>CCA</sub> = 3.3 V, V <sub>CCB</sub> = 5.0 V	15	pF
	Power Dissipation Capacitance <sup>(8)</sup>	A to B	$V_{CCA} = 3.3 \text{ V},$	55	s E
C <sub>PD</sub>	Fower Dissipation Capacitance	B to A	$V_{CCB} = 5.0 \text{ V}$	40	pF

#### Note:

8. C<sub>PD</sub> is measured at 10 MHz.

## 8-Bit Dual-Supply Translating Transceiver

The 74LVX3245 is a dual-supply device capable of bidirectional signal translation. This level shifting ability provides an efficient interface between low-voltage CPU local bus with memory and a standard bus defined by 5 V I/O levels. The device control inputs can be controlled by the low-voltage CPU and core logic or a bus arbitrator with 5 V I/O levels.

Manufactured on a sub-micron CMOS process, the 74LVX3245 is ideal for mixed voltage applications such as notebook computers using 3.3 V CPUs and 5 V peripheral devices.

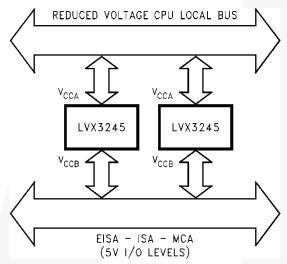


Figure 4. Application Example

### **Power-Up Considerations**

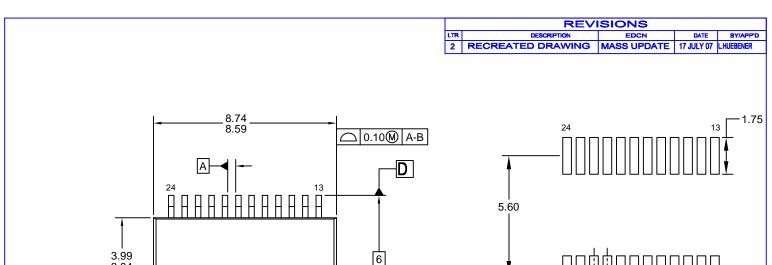
To ensure that the system does not experience unnecessary I<sub>CC</sub> current draw, bus contention, or oscillations during power up; the following guidelines should be followed to *(refer to Table 2)*:

- Power up the control side of the device first (V<sub>CCA</sub>).
- /OE should ramp with or ahead of V<sub>CCA</sub>. This helps guard against bus contention.
- The Transmit/Receive (T/R) control pin should ramp with V<sub>CCA</sub>. This ensures that the A-port data pins are configured as inputs. With V<sub>CCA</sub> receiving power first, the I/O port should be configured as an input to help guard against bus contention and oscillations.
- A-side data inputs should be driven to a valid logic level. This prevents excessive current draw.

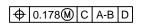
The above steps ensure that there are no bus contentions or oscillations, and therefore no excessive current draw occurs during the power-up cycling. These steps help prevent possible damage to the translator devices and potential damage to other system components.

Table 2. Low Voltage Translator Power-Up Sequencing

Device	V <sub>CCA</sub>	V <sub>CCB</sub>	T/R	/OE	A-Side I/O	B-Side I/O	Floatable Pin Allowed
74LVX3245	3 V (Power-Up First)	5 V Configurable	Ramp with V <sub>CCA</sub>	Ramp with V <sub>CCA</sub>	Logic 0 V or V <sub>CCA</sub>	Outputs	No

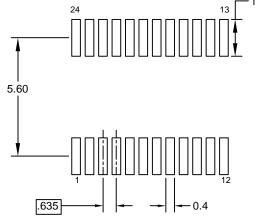


# **TOP VIEW**

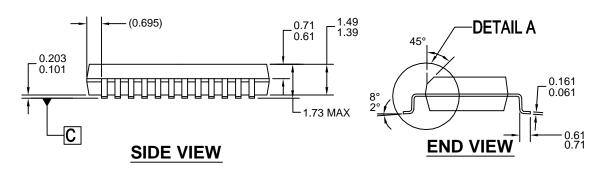


24X 0.3 0.2

0.20**M** C **2X 12 TIPS** 



# **LAND PATTERN RECOMMENDATION**



### NOTES:

A. THIS PACKAGE CONFORMS TO JEDEC M0-137 VARIATION AE

3.84

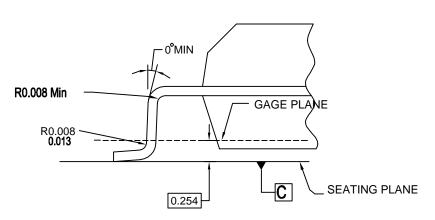
0.10M A-B

0

0.635

В

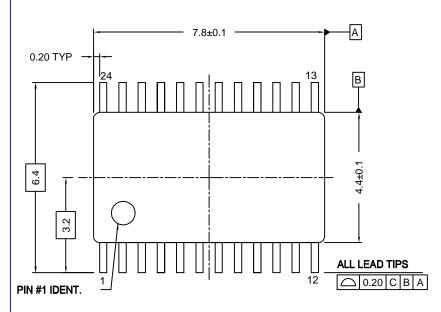
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DRAWING CONFORMS TO ASME Y14.5M-1994
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- E. LAND PATTERN STANDARD: SOP63P600X175-24M
- F. DRAWING FILE NAME: MKT-MQA24REV2

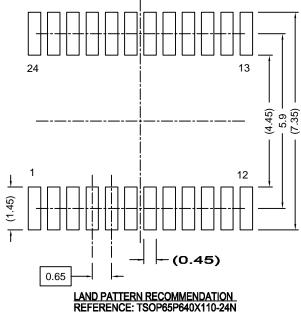


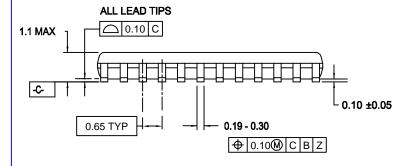
# **DETAIL A**

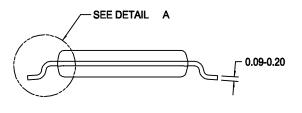
APPROVALS	DATE	FAIRC	:HIL	<b>B</b>		
L.HUEBENER 1:	7 JULY 07	SEMICON				
H.ALLEN 3	0 JULY 07	24LD, QSOP, JEDEC MO-137,				
ENGR. CHK.		2125, Q001, 02520 IIIO 107,				
				3.9 MM	WIDE	
				J.Y IVIIVI		
PROJECTION	_	SCALE	SIZE	DRAWING NUMBER		REV
	_	N/A	N/A	MKT	-MQA24	2
INCH IMMI	_	DO NOT SCALE DRAWING SHEET 1 of 1			f 1	

REVISIONS						
	LTR	DESCRIPTION	EDCN	DATE	BY/APP'D	
		CHANGE TO FSPM DRAWING FORMAT N LEAD SHIFT TOL. FROM 0.13MM TO 0.10MM	ECN-MTC24REV4	21/12/2006	H.ALLEN	







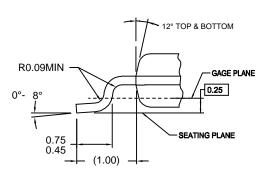


#### DIMENSIONS ARE IN MILLIMETERS

#### **NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AD, DATE 10/97.
- **B. DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994
- E. DRAWING FILE NAME: MTC24REV4

MTC24REV4



**DETAIL** A

APPROVALS PRAWN FEITAN	<b>DATE</b> 8-10-99	FAIRC		Dayan	Lepas, FIZ, , Penang, Malaysia	
DFTG. CHK.  H.ALLEN ENGR. CHK.	21-12-2006	24LD, TSSOP, JEDEC MO-153, 4.4MM WIDE				
PROJECTION		SCALE N/A	SIZE A4	DRAWING NUMBER	Γ-MTC24	REV 4
		DO NOT SCALE DRAWING			SHEET 1 of	1





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EfficientMax™ ESBC™

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Gmax™ ISOPLANAR™

MIČROCOUPLER™ MicroFET™

MicroPak™ MicroPak2™ MillerDrive™ MotionMax™ MotionGrid® MTi<sup>®</sup> MTx® MVN® mWSaver®

OptoHiT™ OPTOLOGIC® OPTOPLANAR®

PowerTrench® PowerXS™

Programmable Active Droop™

**QFET** QS™ Quiet Series™ RapidConfigure™

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SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEAL TH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SyncFET™ Sync-Lock™

SYSTEM SYSTEM

TinyBoost<sup>®</sup> TinyBuck<sup>®</sup> TinyCalc™ TinyLogic<sup>®</sup> TINYOPTO™ TinvPower™ TinyPWM™ TinyWire™ TranSiC™

TriFault Detect™ TRUECURRENT®\* uSerDes™

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Definition of Terms					
<b>Datasheet Identification</b>	Product Status	Definition			
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
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Rev. 172